

Peak Emission Wavelength: 1050nm



Description

- Size 1206: 3.2 (L) x 1.6 (W) x 1.2 (H) mm
- Circuit substrate: glass laminated epoxy
- Devices are RoHS conform
- Lead free solderable, soldering pads: gold plated
- Taped in 8 mm blister tape, cathode to transporting perforation
- All devices are sorted into radiant intensity classes
- High radiation intensity types

Absolute Maximum Ratings (Ta=25°C)



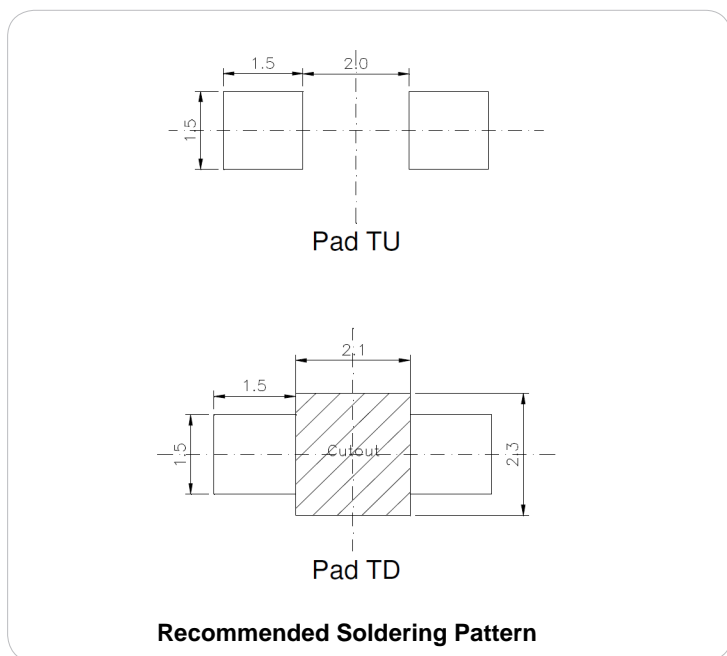
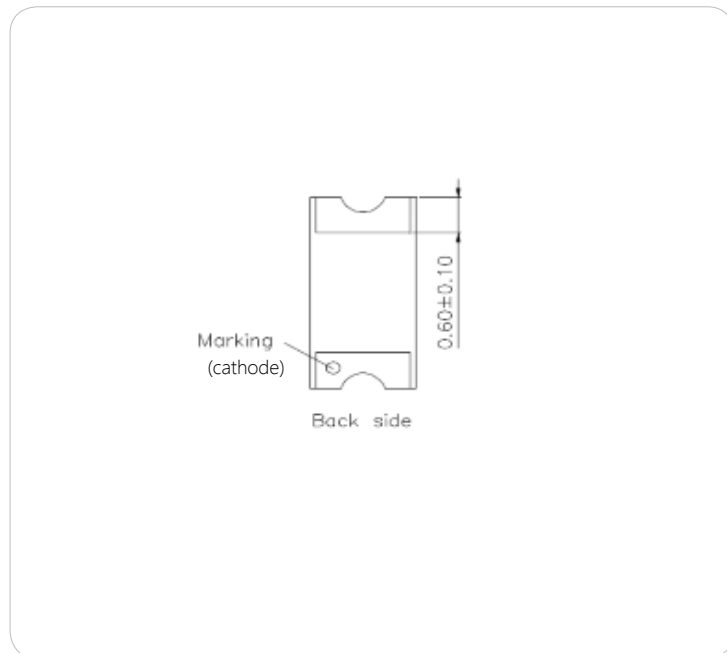
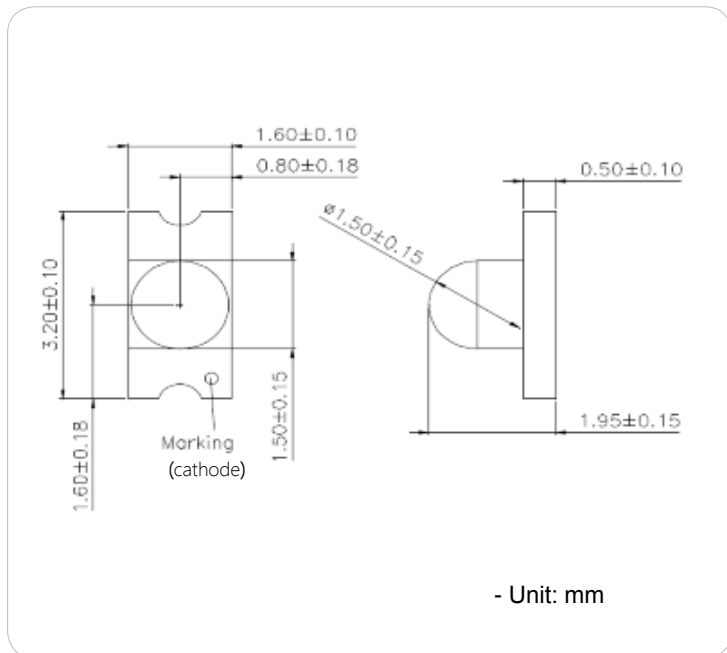
ITEMS	SYMBOL	RATINGS	UNIT
Forward DC Current	If	50	mA
Peak Forward Current *	Ifp	250	mA
Reverse Voltage	Vr	5	V
Reverse Current	Ir	100	uA
Operating Temperature	Top	-40 to +85	°C
Storage Temperature	Tst	-55 to +85	°C
Thermal Resistance RthJA		450	K/W

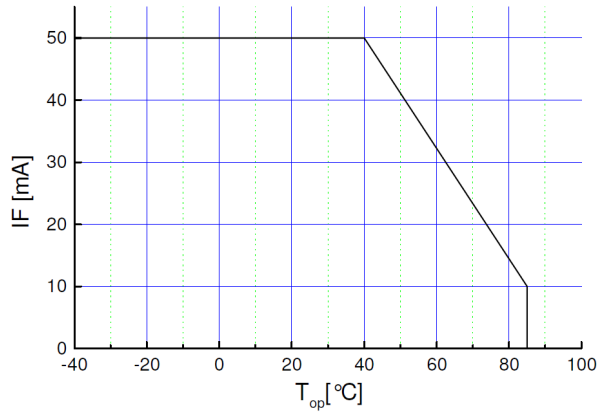
* tp ≤ 100 us, T=1:10

Electrical & Optical Characteristics (Ta = 25°C)

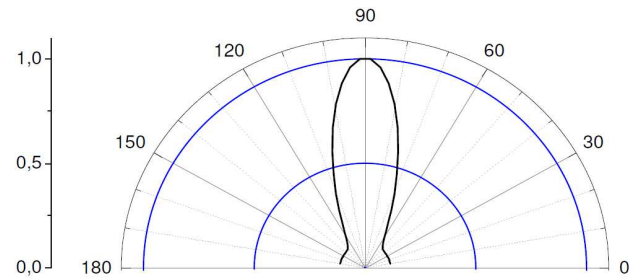
ITEMS	SYMBOL	MIN	TYP	MAX	UNIT
Forward Current	If	--	--	50	mA
Forward Voltage	Vf	--	1.3	1.5	V
Peak Wavelength	λp	1040	1050	1060	nm
Power Output	Po	--	4	--	mW
Switching Time	Tr, Tf	--	20	--	ns

Package Dimensions



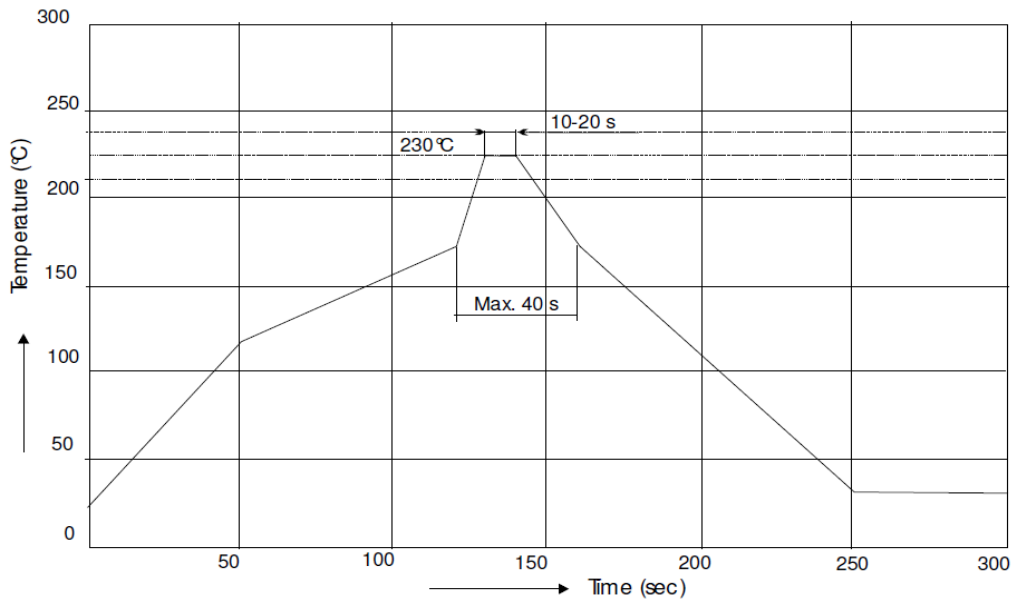


**Maximal
forward
current (DC)
characteristic**

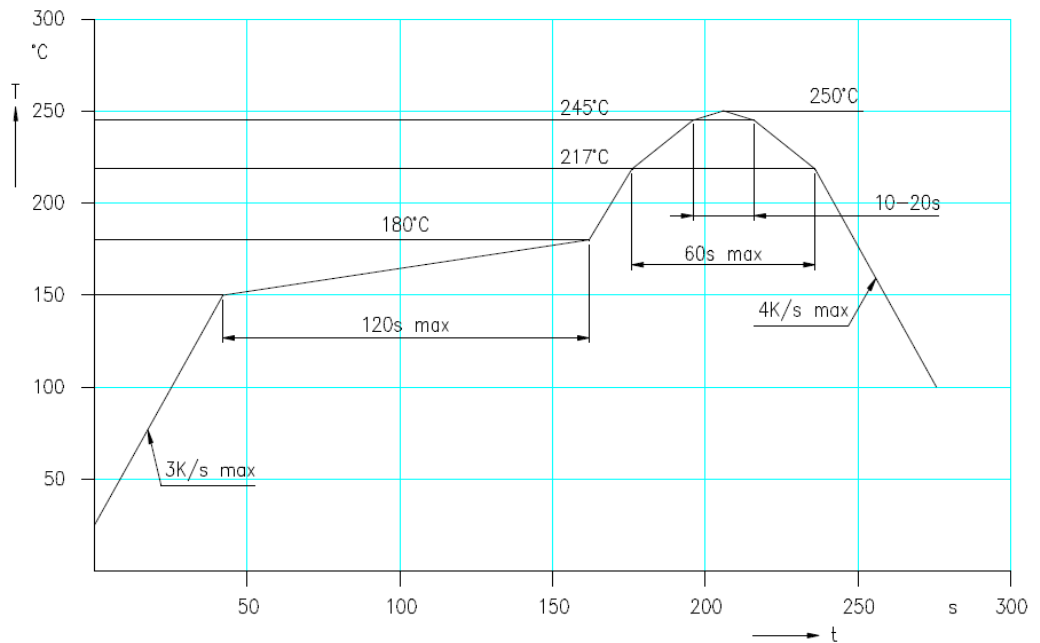


View angle

IR reflow soldering profile



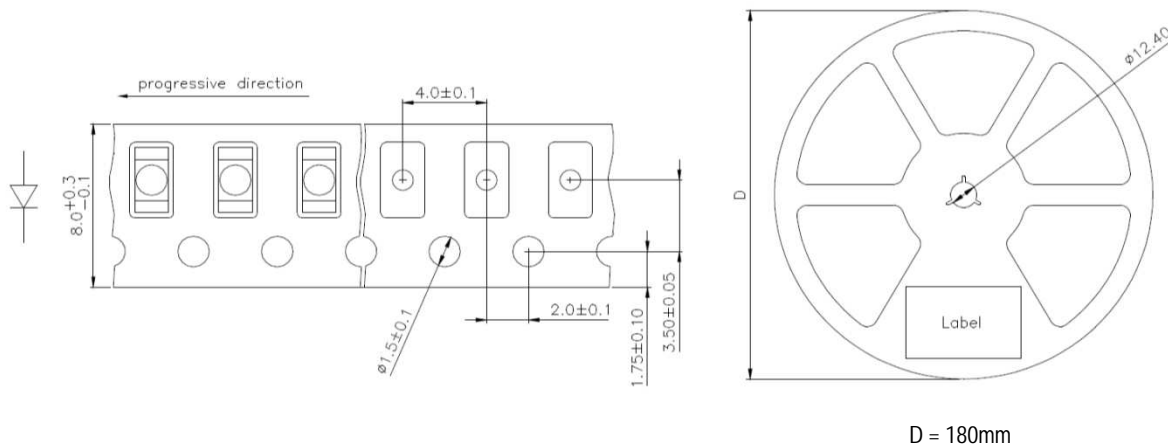
IR reflow soldering profile for lead free soldering



Manual soldering:
max power of iron 25 W / 3 s / 300°C

Measured according to CIE 127. All SMD-LEDs are 100% measured and selected on full automated equipment with an accuracy of $\pm 11\%$.

Tape and Reel packing



Tape and Reel -Suffice to the part number	
Ex:	MTXXXX-T05 = 500 piece reel
Code	Components per reel
T05	500
T1	1000
T2	2000
T25	2500
T3	3000

Packing: The reel is seaLED in special plastic bag with integrate ESD protection (MIL - STD 81705) including a silica dry-pack